

02-28-2006

To the Director, U.S. Patent and Trademark

1al documents or copy thereof.



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1. Name of conveying party(ies): (List using letters or numbers for multiple parties) Chen-Jean Chou Additional name(s) of conveying party(ies) attached? () Yes (X) No		Name: QUALCOMM MEMS Technologies, Inc. Street Address: 5775 Morehouse Drive City: San Diego State: California ZIP: 92121 Additional name(s) of receiving party(ies) attached? () Yes (X) No	
3. Nature of conveyance: (X) Assignment () Security Agreement () Merger () Change of Name () Other: Execution Date: (List as in section 1 if multiple signatures) February 16, 2006		4. US or PCT Application number(s) or US Patent number(s): (X) Application(s) filed herewith Additional numbers attached? () Yes (X) No	
5. Party to whom correspondence concerning document should be mailed: Customer No. 59,747 Address: Knobbe, Martens, Olson & Bear, LLP 2040 Main Street, 14 th Floor Irvine, CA 92614 Return Fax: (949) 760-9502 Attorney's Docket No.: QCO.055A		6. Total number of applications and patents involved: 1	
7. Total fee (37 CFR 1.21(h)): \$40 (X) Enclosed		8. Deposit account number: 11-1410 Please charge this account for any additional fees which may be required, or credit any overpayment to this account.	
9. Statement and signature. To the best of my knowledge and belief, the foregoing information is true and correct, and any attached copy is a true copy of the original document. <div style="display: flex; justify-content: space-between;"><div><u>Eric M. Nelson</u> Name of Person Signing 45,664 Registration No.</div><div> Signature</div><div><u>2/21/2006</u> Date</div></div> <div style="text-align: center;">Total number of pages including cover sheet, attachments and document: 2</div>			

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ASSIGNMENT

WHEREAS, I, Chen-Jean Chou, a U.S.A. citizen, residing at 21 Ridgefield Road, New York, New York, 10956, have invented certain new and useful improvements in a METHOD FOR PROVIDING AND REMOVING DISCHARGING INTERCONNECT FOR CHIP-ON-GLASS OUTPUT LEADS AND STRUCTURES THEREOF for which I have executed an application for Letters Patent in the United States, on even date herewith;

AND WHEREAS, QUALCOMM MEMS Technologies, Inc. (hereinafter "ASSIGNEE"), a Delaware Corporation, with its principal place of business at 5775 Morehouse Drive, San Diego, CA 92121, desires to acquire the entire right, title, and interest in and to the said improvements and the said Application:

NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00) to me in hand paid, and other good and valuable consideration, the receipt of which is hereby acknowledged, I, the said inventor, do hereby acknowledge that I have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, the entire right, title, and interest throughout the world in, to and under the said improvements, and the said application and all provisional applications relating thereto, and all divisions, renewals and continuations thereof, and all Letters Patent of the United States which may be granted thereon and all reissues and extensions thereof, and all rights of priority under International Conventions and applications for Letters Patent which may hereafter be filed for said improvements in any country or countries foreign to the United States, and all Letters Patent which may be granted for said improvements in any country or countries foreign to the United States and all extensions, renewals and reissues thereof; and I hereby authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said improvements to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND I DO HEREBY sell, assign, transfer, and convey to ASSIGNEE, its successors, legal representatives, and assigns all claims for damages and all remedies arising out of any violation of the rights assigned hereby that may have accrued prior to the date of assignment to ASSIGNEE, or may accrue hereafter, including, but not limited to, the right to sue for, collect, and retain damages for past infringements of the said Letters Patent before or after issuance.

AND I HEREBY covenant and agree that I will communicate to the said ASSIGNEE, its successors, legal representatives and assigns, any facts known to me respecting said improvements, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said improvements in all countries.

IN TESTIMONY WHEREOF, I hereunto set my hand and seal this 16th day of Feb, 2006


Chen-Jean Chou

IN TESTIMONY WHEREOF, acknowledged by QUALCOMM MEMS Technologies, Inc.

this _____ day of _____, 2005.

QUALCOMM MEMS Technologies, Inc.

Name: _____
Title: _____

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